

In re: Byung-jun Park  
Serial No.: To Be Assigned  
Filed: Currently Herewith  
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**In the Specification:**

At page 1, line 2, please change the title as follows:

INTEGRATED CIRCUITS HAVING SELF-ALIGNED METAL CONTACT  
STRUCTURES ~~AND METHODS OF FABRICATING SAME~~

On page 1, after the title, please insert a section entitled "Related Application" as follows:

**Related Applications**

The present application is a divisional of United States Application Serial No. 10/172,760, filed June 14, 2002, <sup>now Patent No. 6,710,466</sup> entitled *Method of Fabricating Integrated Circuit Having Self-Aligned Metal Contact Structure*, the disclosure of which is hereby incorporated herein by reference.